CS20 Product Manual

| Revision of previous versions | | | | | |
|-------------------------------|---------|--|-------------|--|--|
| Date | Version | Description | Author | | |
| September 6, 2022 | V1.0 | | Terry/Daisy | | |
| December 20, 2022 | V1.1 | The single frequency parameter of CS20 is added | Terry | | |
| February 3, 2023 | V1.2 | Modify the description of the dual-frequency parameter | Terry | | |
| December 6, 2023 | V1.3 | Modify the dimension description | Terry | | |

Catalog

| 1. Description and characteristics |
|--|
| 2. Introduction2 |
| 2.1 Purpose of this document2 |
| 2.2 Overview of ToF (Time of Flight) technology2 |
| 2.3 Block diagram of a solid-state LiDAR system4 |
| 2.4 Technical parameters5 |
| 3.Component specifications |
| 3.1 ToF modules6 |
| 3.1.1 ToF module image sensor6 |
| 3.1.2 ToF module laser emitter6 |
| 3.2 ISP motherboard7 |
| 3.3 power consumption8 |
| 4. Performance evaluation9 |
| 5. Mechanical structure10 |
| 6. Storage conditions11 |
| 7.Camera Cleaning Steps11 |
| 8.Software11 |
| 9. Regulatory Compliance12 |
| Disclaimer |

1. Description and characteristics

Product Description:

CS20 is a solid-state LiDAR, equipped with a ToF image sensor with a resolution of 640*480, which uses ToF technology to obtain threedimensional information of objects and space, with excellent performance such as long distance and low power consumption, providing users with convenient and efficient 3D perception capabilities.

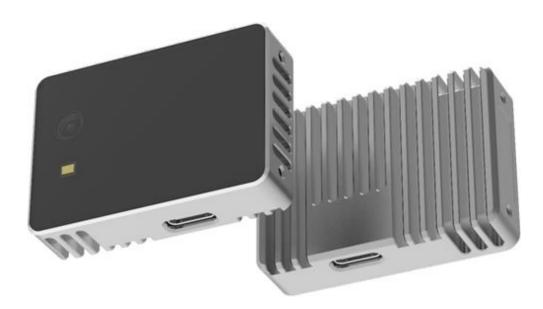
The product is powered through the Type C interface and outputs depth image phase information at the same time, and users can obtain depth, IR, point cloud and other data through the SDK.

Features

- •Centimeter-level measurement accuracy
- Measuring range: 0.1-3.75m @90% Ref
- High dynamic measuring range
- Support depth and signal amplitude timing synchronization
- Adjustable capacity and resolution

Applicable scenarios

- Robot obstacle avoidance
- Industrial vision
- Volumetric measurements
- Liveness detection
- Somatosensory interaction
- 3D modeling



2. Introduction

2.1 Purpose of this document

This document details the specifications of the CS20 solid-state LiDAR and provides users with the relevant information they need to understand and use the CS20 solid-state LiDAR.

2.2 Overview of ToF (Time of Flight) technology

ToF technology calculates the distance between an object and the camera by the time of flight of light. First, the ToF sensor gives the modulation signal to the light source driver chip, and then the modulation signal emits high-frequency modulated near-infrared light by controlling the laser, and when the light encounters the measured object, it is diffusely reflected back to the sensor receiver, and the depth information is calculated by the time difference between the emitted and received light.

The CS20 solid-state LiDAR uses continuous wave modulation (CWiToF) in i-ToF (indirect ToF). Through the proportional relationship of the energy value collected by the sensor in different time windows, the signal phase is analyzed, and the time difference between the transmitted signal and the received signal is indirectly measured, and then the depth is obtained.

Continuous Wave Modulation (K-Itov)

Sine wave modulation is usually used, and the phase offset of the sine wave at the receiving and transmitting ends is proportional to the distance of the object from the camera, and the distance is measured by the phase offset

$$\varphi_{TOF} = \operatorname{atan}\left(\frac{C_1 - C_3}{C_2 - C_4}\right)$$
$$D = \frac{c}{2} * \frac{\varphi_{TOF}}{2\pi * f_m} + D_{offset}$$

Formula 2-1. Distance calculation

The phase offset (ϕ) and depth (D) are obtained from the integrated energy values parsed from the above equations C1, C2, C3, and C4, which are the energies collected by the receiving windows of four different phase delays, corresponding to the samples at the phase sampling points at 0°, 90°, 180°, and 270°, respectively, namely:

$$C_{1} = Asin(\varphi)$$

$$C_{2} = Asin(\varphi + 90^{\circ}) = Acos(\varphi)$$

$$C_{3} = Asin(\varphi + 180^{\circ}) = -Asin(\varphi)$$

$$C_{4} = Asin(\varphi + 270^{\circ}) = -Acos(\varphi)$$

where A is the amplitude of the received sinusoidal signal.

In terms of accuracy, the accuracy of CW-iToF is mainly constrained by random noise, which is inversely proportional to the signal-to-noise ratio (SNR) of the received optical signal, and quantization noise, which is inversely proportional to the frequency of sine wave modulation. Therefore, in order to improve the accuracy, CW-iToF generally uses high-power short-integration time sampling to improve the SNR of the received optical signal, and at the same time increases the modulation frequency to suppress the quantization noise.

In terms of range, CW-iToF can resolve the phase range of $[0~2\pi]$, so its maximum range is Dmax=c/(2fm). That is, the higher the frequency, the higher the accuracy and the smaller the measuring range. If the depth of the range is exceeded, a periodic phase wrap will occur, and the measured value will fall incorrectly within [0~Dmax].

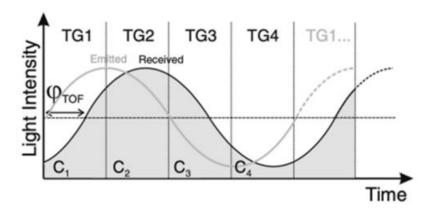


Figure 2-1. Light flight time vs. light intensity

2.3 Block diagram of a solid-state LiDAR system

The CS20 solid-state LiDAR hardware system consists of two main components, the ISP processor and the Depth module. The ISP processor is located on the motherboard, and the ToF module is fastened to the motherboard through connectors.

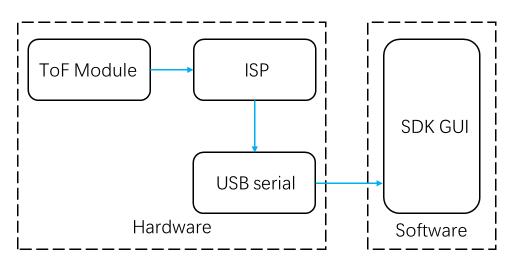


Figure 2-2.Block diagram of the CS20 solid-state LiDAR system

2.4 Technical parameters

| | | Technical parameters | | | |
|-------------|-----------------------|-------------------------------------|--|--|--|
| | Resolution*1 | 640*480@8fps/320*240@20fps | | | |
| Depth image | Resolution*2 | 320*240@25fps | | | |
| | FOV | H60°xV45° | | | |
| | Working distance*1 | 0.1-5m, indoor | | | |
| | Working distance*2 | 0.1-3.75m, indoor | | | |
| | Accuracy*1 | 0.1~0.5m@±2.5cm; 0.5~5m@±1% | | | |
| | Accuracy*2 | 0.1~0.5m@±2.5cm; 0.5~3.75m@±1.5% | | | |
| | VCSEL wavelength | 940nm | | | |
| Basic | Product dimensions | 48mm x 34mm x 12mm | | | |
| parameters | Data transmission | USB 2.0 protocol , Type C Interface | | | |
| | Power supply mode | 5V, average 0.5A | | | |
| | power consumption | average 1.2W | | | |
| | operating system | Win 10, Linux, ROS | | | |
| | Operating temperature | -10 ~ 50°C | | | |
| | security | Laser CLASS1 | | | |

Note: a.*1 and *2 are single and dual-frequency difference parameters, where *1 is the CS20 dual-frequency parameter, which is suitable for static scenarios. *2 is a CS20 single-frequency parameter, which is suitable for dynamic scenes.

b. Absolute accuracy test conditions: shoot 90% Ref chart at different distances, take 10*10 pixels in the center, and repeat 15 times to take the average value.

3. Component specifications

3.1 ToF modules

The ToF module components are as follows:

| compose | description | | | |
|------------------|---|--|--|--|
| ToF imager | Time of light image sensor | | | |
| ToF emitter | Class 1 laser compliant (optional) | | | |
| Other Components | Laser Driver, EEPROM, Voltage Regulators, | | | |
| Other Components | FPC, Connector etc. | | | |

Table 3-1. ToF module components

3.1.1 ToF module image sensor

| compose | description |
|--------------------------|----------------------|
| Active Pixels | 320*240 |
| Sensor Aspect Ration | 4: 3 |
| Format | 10-bit RAW |
| Shutter Type | Global shutter |
| Signal Interface | MIPI CSI-2, 2X Lanes |
| F Number | 1.4 |
| Effect Focal Length | 3.90mm |
| Focus | Fixed |
| Horizontal Field of View | 59.2 |
| Vertical Field of View | 46.0 |
| Diagonal Field of View | 71.0 |
| TV Distortion (Trad.*2) | <1.5% |

Table 3-2. ToF module image sensor parameters

3.1.2 ToF module laser emitter

The ToF laser emitter emits uniform near-infrared (940nm) light to the object, and the laser emitter meets the safety requirements of Class 1 lasers under normal operating conditions.

| ltems | Test Condition | Min | Typical | Max | Unit |
|--------------------------------|------------------|-----|---------|-----|-------|
| Optical Output power | Pulse=3.5A, 50°C | 2.3 | 2.7 | - | W |
| Threshold current | Pulse 50°C | 0.3 | 0.45 | 0.7 | А |
| Operating Current | Pulse 50°C | - | 3.5 | - | А |
| Operating voltage | Pulse=3.5A, 50°C | - | 2.14 | 2.6 | V |
| Slope efficient | Pulse=3.5A, 50°C | 0.8 | 1 | - | mW/mA |
| Power conversion efficiency | Pulse=3.5A, 50°C | 33 | 36 | - | % |
| Angle | Pulse=3.5A, 50°C | - | 72 | - | 0 |
| Angle | Pulse=3.5A, 50°C | - | 58 | - | |
| Wavelength | lf=6A, 50°C | 930 | 940 | 950 | nm |
| Wavelength coefficient | Pulse=3.5A | - | 0.07 | - | nm/°C |

Table 3-3. Parameters of the laser emitter of the ToF module

3.2 ISP motherboard

| Components | Description |
|-------------------------|--|
| ISP Processor | PC Camera Controller |
| 8 MB Flash | PC Camera Controller firmware storage and ToF firmware storage |
| 24 MHz Crystal | Clock source for Vision Processor |
| Depth Module Receptacle | (36+10)pin receptacle for connection to Depth Module |
| USB Type-C | USB peripheral connector for connection to Host USB 2.0 port |
| Voltage Regulators | DC to DC and LDO converters powering Vision Processor Board and depth module |
| Mounting holes | Vision Processor Board secure mounting |

Table 3-5.ISP motherboard components

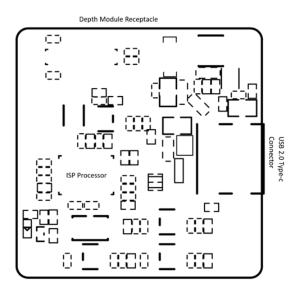


Figure 3-1. Schematic diagram of the CS20 ISP motherboard

| Dimension | Min | Nominal | Max | Unit |
|-----------|-------|---------|------|------|
| Width | 30.3 | 30.5 | 30.7 | mm |
| Height | 30.08 | 31.0 | 31.2 | mm |
| Depth | 4.85 | 4.90 | 4.95 | mm |
| Weight | 4.45 | 4.50 | 4.55 | g |

Table 3-6. ISP 主板尺寸

3.2.1 Type C description

| Г | A1 | A4 | A5 | A6 | A7 | A8 | A9 | A12 |
|---|-----|------|------|-----|-----|------|------|-----|
| L | GND | VBUS | CC1 | DP1 | DN1 | SBU1 | VBUS | GND |
| L | | | | | | | | |
| L | GND | VBUS | SBU2 | DN2 | DP2 | CC2 | VBUS | GND |
| Г | B12 | B9 | B8 | B7 | B6 | B5 | B4 | B1 |

Figure 3-2. USB Type-C Receptacle Pin Map

| Pin | Signal | Function | Pin | Signal | Function |
|-----|--------|----------------------------|-----|--------|----------------------------|
| A1 | GND | 接地 | B12 | GND | 接地 |
| A4 | VBUS | 总线电源 | B9 | VBUS | 总线电源 |
| A5 | CC1 | Configuration channel | B8 | SBU2 | NC |
| A6 | DP1 | USB 2.0差分信号, position 1, 正 | B7 | | USB 2.0差分信号, position 2, 负 |
| A7 | DN1 | USB 2.0差分信号, position 1, 负 | B6 | DP2 | USB 2.0差分信号, position 2, 正 |
| A8 | SBU1 | NC | B5 | CC2 | Configuration channel |
| A9 | VBUS | 总线电源 | B4 | VBUS | 总线电源 |
| A12 | GND | 接地 | B1 | GND | 接地 |

Figure 3-3. USB Peripheral Connector Pin List

3.3 power consumption

| state | lmin (mA) | lavg (mA) | lpp (mA) | | | |
|---|-----------|-----------|----------|--|--|--|
| Standby(Whole machine) | 91 | 195 | 1896 | | | |
| Standby | 5 | 5 | 5 | | | |
| Supply voltage: VBUS=5V, the measured data is based on exposure time=580us. | | | | | | |

Table 3-7. CS20 solid-state LiDAR power consumption metrics

4. Performance evaluation

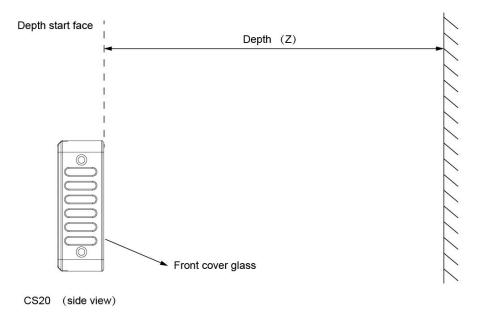


Figure 4-1 CS20 Review Starting Point

 Absolute accuracy: refers to the difference between the measurement result and the true value, which is used to characterize the proximity of the measurement result to the true value, and its formula is defined as follows:

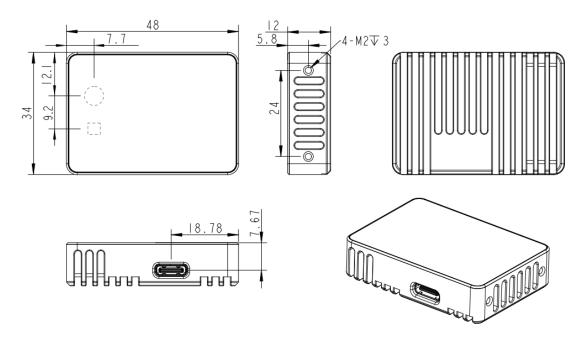
$$Accuracy = \frac{\sum_{i} depth_i}{N} - D$$

2) Inter-frame noise: It is used to evaluate the stability of depth data between multiple frames, and the formula of inter-frame noise is defined as follows:

$$Temporal \ noise = \frac{1}{N} \sum_{i} \sqrt{\frac{\sum_{j} \left(depth_{j} - \frac{\sum_{j} depth_{j}}{M} \right)^{2}}{M}}$$

 Point cloud thickness: Take pictures of the white wall and test the point cloud thickness of the white wall at different distances

5. Mechanical structure



| Dimension | Min | Nominal | Max | Unit |
|-----------|-------|---------|-------|------|
| Width | 47.74 | 47.94 | 48.14 | mm |
| Height | 33.8 | 34 | 34.2 | mm |
| Depth | 11.8 | 12 | 12.2 | mm |
| Weight | 32.5 | 33 | 33.5 | g |

Table 5-1. Structural dimensions

6. Storage conditions

| Condition | Description | Min | Мах | Unit | |
|---------------------|-------------|--------------------------|-----|------|--|
| Storage | | -15 | 60 | °C | |
| Temperature | Humidity | Temperature/RH: 40°C/90% | | | |
| Work Temperature | | -10 | 50 | °C | |

7. Camera Cleaning Steps

1. Do not use any chemicals or water on the camera lens.

2. Use the lens purge brush to remove as much dust and dirt as possible

from the lens.

3. Wipe with a dry, clean microfiber cloth.

8.Software

• Windows client---Credimension Viewer

Credimension Viewer CS20 series of windows demo GUI tools. This tool is mainly used to obtain, display, and save Depth, IR, and Point cloud information, and also supports functions such as viewing basic device information, setting resolution, integration time, etc.

• SDK---CSAPI

Customers can use the CS20 SDK for secondary development, which supports Windows/Linux (Ubuntu/ARMv7/ARMv8)/ROS platforms, and has specific performance optimizations for the embedded architecture.

9. Regulatory Compliance

" ROHS、CE、FCC、CLASS 1 "

Disclaimer

Device application information and other similar content described in this publication is provided for your convenience only and may be superseded by updated information. It is your responsibility to ensure that your application complies with the technical specifications. The Company makes no representations or warranties of any kind, express or implied, written or oral, statutory or otherwise, with respect to such information, including, but not limited to, representations or warranties of use, quality, performance, merchantability or fitness for a particular purpose. The Company shall not be liable for any such information or the consequences arising from the use of such information. This product may not be used as a critical component in a life support system without the written approval of the Company.